

## CLAIMS

5 *at* 1. A method of fabricating an electronic device (38) comprising the steps of:

- (a) forming a predetermined pattern of weakened regions (6) in a layer (2) of rigid material which define contiguous portions (14) of the rigid layer;
- (b) providing electronic components (12) on the rigid layer (2); and
- (c) forming flexible connectors (16) which extend between components (12) on different portions (14).

10 2. A method of Claim 1 including the step of dividing the rigid layer (2) along the weakened regions (6).

15 3. A method of Claim 1 including the step of mounting the rigid layer (2) over a flexible substrate (18).

20 4. A method of Claim 1 wherein the connectors (16) are formed by electroplating metal onto the rigid layer (2).

25 5. A method of Claim 4 wherein a seed layer (30) is deposited prior to electroplating the metal connectors (16).

6. A method of Claim 4 wherein areas of photoresist (24,26,28) are defined over the rigid layer (2) prior to electroplating the metal, such that portions of the connectors (16) form bridges over the photoresist, and the photoresist is subsequently removed.

30 7. A method of fabricating an electronic device (38) comprising the steps of:

- (a) providing electronic components (12) on a rigid layer (2);
- (b) forming flexible connectors (16) which extend between components (12) on different contiguous portions (14) of the rigid layer (2); and

(c) dividing the rigid layer (2) into the contiguous portions (14).

8. A method of Claim 7 including the step of mounting the rigid layer (2) over a flexible substrate (18).

9. A method of Claim 7 wherein the connectors (16) are formed by electroplating metal onto the rigid layer (2).

10. A method of Claim 9 wherein a seed layer (30) is deposited prior to electroplating the metal connectors (16).

11. A method of Claim 9 wherein areas of photoresist (24,26,28) are defined over the rigid layer (2) prior to electroplating the metal, such that portions of the connectors (16) form bridges over the photoresist, and the photoresist is subsequently removed.

12. An electronic device (38) comprising a layer (2) of rigid material having electronic components (12) thereon, contiguous portions (14) of the rigid layer being defined by weakened regions (6) of the rigid layer (2), and flexible connectors (16) extending between components (12) on different portions (14).

13. A device of Claim 12 wherein the weakened regions comprise grooves (6,21) in one or both faces (8,10) of the rigid layer (2).

14. A device of Claim 12 wherein the rigid layer (2) is mounted over a flexible substrate (18).

15. A device of Claim 12 wherein the connectors (16) comprise electroplated metal.

16. A device of Claim 12 wherein the connectors (16) comprise a bridge-like portion.

17. An electronic device (38) comprising a layer (2) of rigid material having electronic components (12) thereon, and flexible connectors (16) extending between components on different contiguous portions (14) of the rigid layer, the rigid layer (2) being divided into the contiguous portions (14) such that the device (38) is flexible.

18. A device of Claim 17 wherein the rigid layer (2) has been divided into the contiguous portions (14) along weakened regions (6) of the rigid layer.

19. A device of Claim 18 wherein the weakened regions comprise grooves (6,21) in one or both faces (8,10) of the rigid layer (2).

20. A device of Claim 17 wherein the rigid layer (2) is mounted over a flexible substrate (18).

21. A device of Claim 17 wherein the connectors (16) comprise electroplated metal.

22. A device of Claim 17 wherein the connectors (16) comprise a bridge-like portion.

23. An article (42) having an electronic device (38) mounted thereon, the electronic device (38) comprising a layer (2) of rigid material having electronic components (12) thereon, contiguous portions (14) of the rigid layer being defined by weakened regions (6) of the rigid layer (2), and flexible connectors (16) extending between components (12) on different portions (14).

24. An article (42) having an electronic device (38) mounted thereon, the electronic device (38) comprising a layer (2) of rigid material having

electronic components (12) thereon, and flexible connectors (16) extending between components on different contiguous portions (14) of the rigid layer, the rigid layer (2) being divided into the contiguous portions (14) such that the device (38) is flexible.

Year	1970	1971	1972	1973	1974	1975	1976	1977	1978	1979	1980	1981	1982	1983	1984	1985	1986	1987	1988	1989	1990	1991	1992	1993	1994	1995	1996	1997	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036	2037	2038	2039	2040	2041	2042	2043	2044	2045	2046	2047	2048	2049	2050	2051	2052	2053	2054	2055	2056	2057	2058	2059	2060	2061	2062	2063	2064	2065	2066	2067	2068	2069	2070	2071	2072	2073	2074	2075	2076	2077	2078	2079	2080	2081	2082	2083	2084	2085	2086	2087	2088	2089	2090	2091	2092	2093	2094	2095	2096	2097	2098	2099	2100
1970	1971	1972	1973	1974	1975	1976	1977	1978	1979	1980	1981	1982	1983	1984	1985	1986	1987	1988	1989	1990	1991	1992	1993	1994	1995	1996	1997	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036	2037	2038	2039	2040	2041	2042	2043	2044	2045	2046	2047	2048	2049	2050	2051	2052	2053	2054	2055	2056	2057	2058	2059	2060	2061	2062	2063	2064	2065	2066	2067	2068	2069	2070	2071	2072	2073	2074	2075	2076	2077	2078	2079	2080	2081	2082	2083	2084	2085	2086	2087	2088	2089	2090	2091	2092	2093	2094	2095	2096	2097	2098	2099	2100	